



DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)} Max	I _D Max T _A = +25°C
60V	8Ω @ V _{GS} = 5V	170mA
000	6Ω @ V _{GS} = 10V	200mA

Features and Benefits

- Dual N-Channel MOSFET
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- · Fast Switching Speed
- Small Surface Mount Package
- ESD Protected Gate, 1KV (HBM)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Qsuffix) part. A listing can be found at https://www.diodes.com/products/automotive/automotive-products/.
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.
 - https://www.diodes.com/quality/product-definitions/
- An Automotive-Compliant Part is Available Under Separate Datasheet (<u>DMN65D8LDWQ</u>)

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- DC-DC Converters
- Power Management Functions
- Battery Operated Systems and Solid-State Relays
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.

Mechanical Data

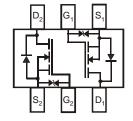
- Case: SOT363 (Standard)
- Case Material: Molded Plastic; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208 @3
- Lead Free Plating (Matte Tin Finish Annealed over Alloy 42 Lead-Frame).
- Terminal Connections: See Diagram
- Weight: 0.006 grams (Approximate)







Top View



Top View Internal Schematic

Ordering Information (Note 4)

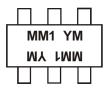
Part Number	Case	Packaging
DMN65D8LDW-7	SOT363 (Standard)	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



 $\begin{array}{l} MM1\text{=}\operatorname{Product}\operatorname{Type}\operatorname{Marking}\operatorname{Code}\\ YM\text{=}\operatorname{Date}\operatorname{Code}\operatorname{Marking}\\ Y\text{ or }\overline{Y}\text{=}\operatorname{Year}\text{ (ex: I = 2021)}\\ M\text{ or }\overline{M}\text{=}\operatorname{Month}\text{ (ex: 9 = September)} \end{array}$

Date Code Key

Year	2007		2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	U			J	K	L	М	N	0	Р	R	S
	,											
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

	Characteristic			Symbol	Value	Units
Drain-Source Voltage				V_{DSS}	60	V
Gate-Source Voltage				V_{GSS}	±20	V
Continuous Drain Current (Note 5)	V _{GS} = 10V	Steady State	T _A = +25°C T _A = +70°C	I _D	180 140	mA
Continuous Drain Current (Note 5)	V _{GS} = 5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	150 120	mA
Continuous Drain Current (Note 6)	V _{GS} = 10V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	200 160	mA
Continuous Drain Current (Note 6)	V _{GS} = 5V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	170 140	mA
Pulsed Drain Current (10µs pulse, dut	y cycle = 1%)			I _{DM}	800	mA

Thermal Characteristics

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	PD	300	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	435	°C/W
Total Power Dissipation (Note 6)	P _D	400	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ heta JA}$	330	°C/W
Thermal Resistance, Junction to Case (Note 6)	R ₀ JC	139	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C



Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)				•	•		
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current $T_J = +25^{\circ}\text{C}$ $T_J = +125^{\circ}\text{C}$ (Note 8)	I _{DSS}	_	_	1.0 5.0	μA	V _{DS} = 60V, V _{GS} = 0V	
Gate-Body Leakage	I _{GSS}	_	_	±5.0	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	$V_{GS(th)}$	1.0	_	2.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance	D	_	2.2	8	Ω	$V_{GS} = 5V, I_D = 0.115A$	
Static Diam-Source On-Resistance	R _{DS (ON)}	_	2.0	6	Ω	$V_{GS} = 10V, I_D = 0.115A$	
Forward Transconductance	g FS	80		_	mS	$V_{DS} = 10V, I_D = 0.115A$	
Diode Forward Voltage	V_{SD}	_	0.8	1.2	V	V _{GS} = 0V, I _S = 115mA	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	22.0	_			
Output Capacitance	Coss	_	3.2	_	pF	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$	
Reverse Transfer Capacitance	C _{rss}	_	2.0	_			
Gate Resistance	R _G	_	79.9	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge V _{GS} = 10V	Qg	_	0.87	_			
Total Gate Charge V _{GS} = 4.5V	Qg	_	0.43	_		$V_{GS} = 10V, V_{DS} = 30V,$	
Gate-Source Charge	Q _{gs}	_	0.11	_	nC	$I_D = 150 \text{mA}$	
Gate-Drain Charge	Q _{gd}	_	0.11	_			
Turn-On Delay Time	t _{D(on)}	—	3.3	_			
Turn-On Rise Time	t _r	_	3.2	_	nS	$V_{DD} = 30V, I_D = 0.115A, V_{GEN} = 10V$	
Turn-Off Delay Time	t _{D(off)}		12.0	_		$R_{GEN} = 25\Omega$	
Turn-Off Fall Time	t _f		6.3				

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper pad layout 7. Short duration pulse test used to minimize self-heating effect.
 8. Guaranteed by design. Not subject to production testing.



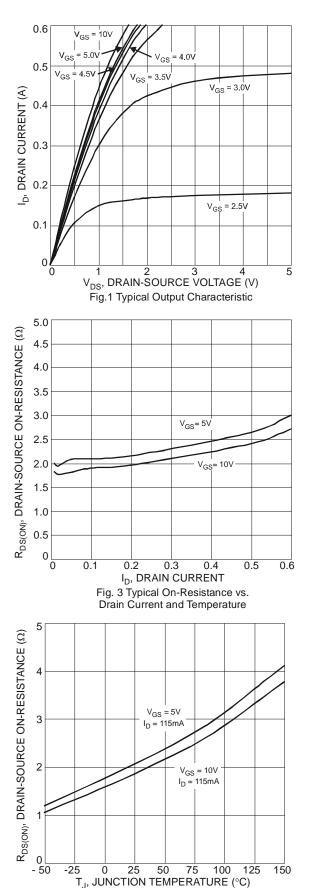
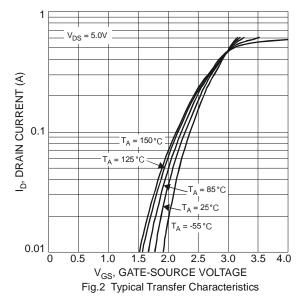


Fig. 5 On-Resistance Variation with Temperature



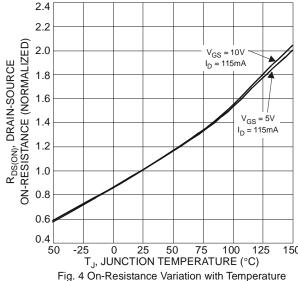
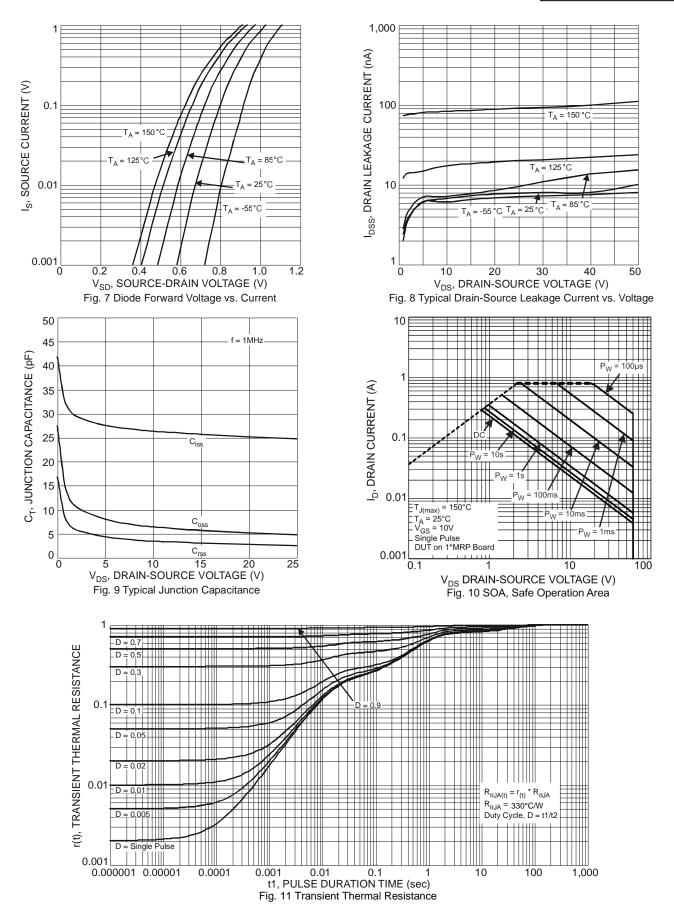


Fig. 6 Gate Threshold Variation vs. Ambient Temperature



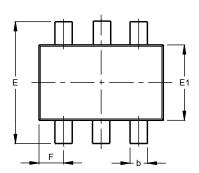


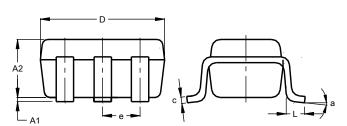


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363 (Standard)



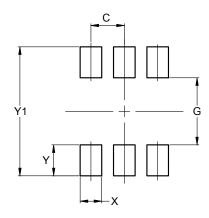


SOT363 (Standard)							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.80	1.00	0.90				
b	0.10	0.35	0.225				
C	0.08	0.22	0.15				
ם	1.80	2.20	2.00				
Е	2.00	2.45	2.225				
E1	1.15	1.35	1.25				
e		1	0.65				
F	0.25	0.45	0.35				
L	0.25	0.46	0.355				
а	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363 (Standard)



Dimensions	Value
Dilliensions	(in mm)
С	0.650
G	1.300
Х	0.420
Y	0.600
Y1	2.500



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